

## FEATURES

- | 30W Peak Pulse Power per Line (tp=8/20μs)
- | Protects four I/O lines
- | Operating voltage: 5 V
- | Ultra Low Capacitance:0.4pF typical  
(I/O to GND)

## APPLICATIONS

- | USB2.0,USB3.0,Ethernet
- | HDMI2.0,Displayport 1.3,eSATA
- | Unified Display Interface
- | Digital Visual Interface
- | High Speed Serial Interface



DFN2510-10L

0524P

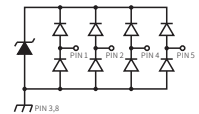
Marking

## IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±25kV (air), ±20kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

## APPROVALS

<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003



Schematic Symbol

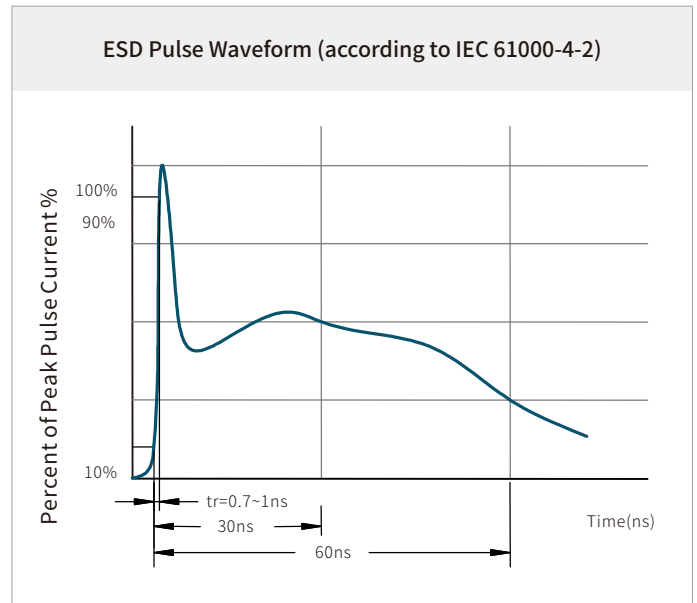
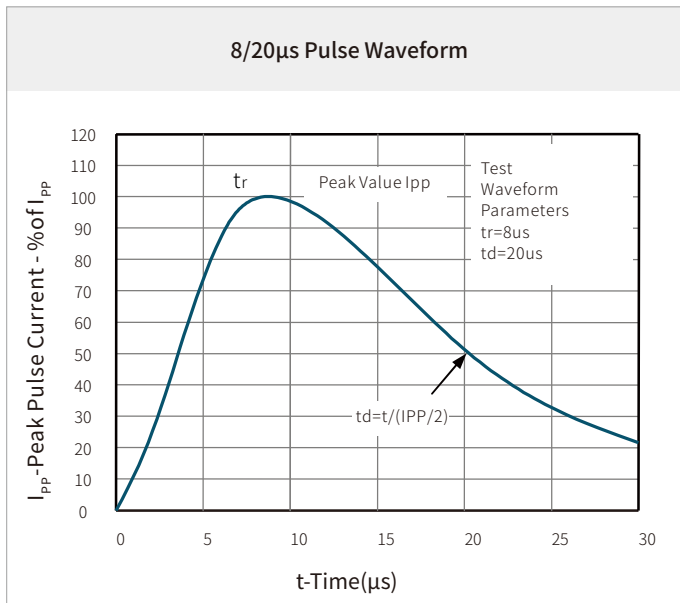
## THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
$P_{PP}$	Peak Pulse Power (tp=8/20μs waveform)	30	Watts
$T_J$	Operating Temperature Range	-55 to +150	°C
$T_{STG}$	Storage Temperature Range	-55 to +150	°C

## ELECTRICAL CHARACTERISTICS

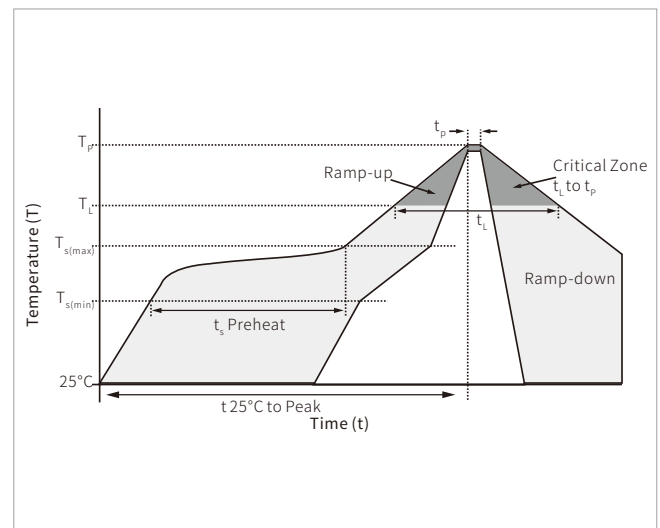
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$V_{RWM}$	Reverse Stand-off Voltage				5	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T=1mA$	6			V
$I_R$	Reverse Leakage Current	$V_{RWM}=5V$			1	μA
$V_C$	Clamping Voltage	$I_{PP}=3A, tp=8/20μs$			12	V
$I_{PP}$	Peak Pulse Current	tp=8/20μs			3	A
$C_J$	Off State Junction Capacitance	$V_R=0V, f=1MHz$ I/O-I/O		0.2		pF
$C_J$	Off State Junction Capacitance	$V_R=0V, f=1MHz$ I/O-GND		0.4		pF

## CHARACTERISTIC CURVES

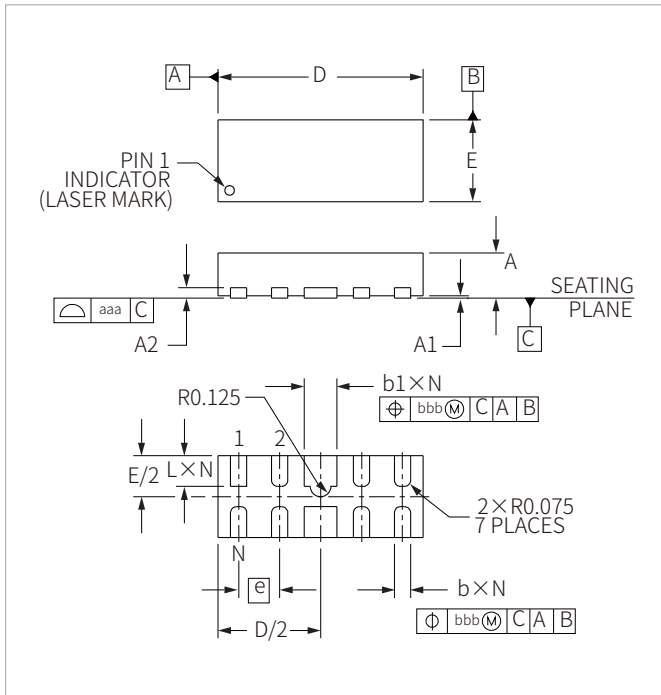


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

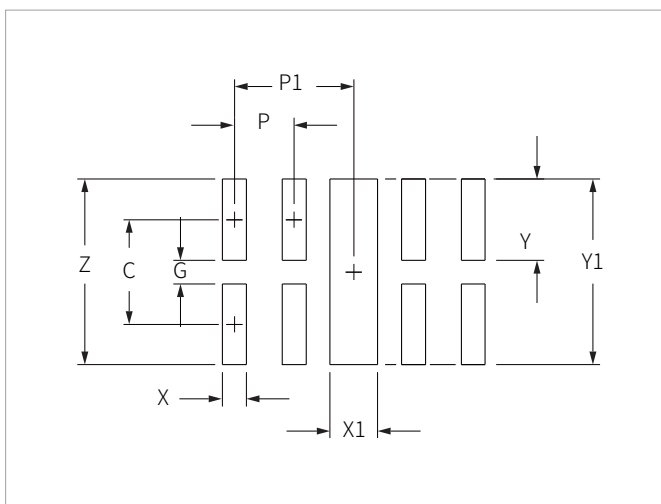


## DFN2510-10L PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.40	0.65	0.016	0.026
A1	0	0.05	0	0.002
A2	(0.13)		(0.005)	
b	0.15	0.25	0.006	0.010
b1	0.35	0.45	0.014	0.018
D	2.40	2.60	0.094	0.102
E	0.90	1.10	0.035	0.043
e	0.50BSC		0.020BSC	
L	0.30	0.45	0.012	0.018
N	8		8	
aaa	0.08		0.003	
bbb	0.10		0.004	

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
C	0.87	0.034
G	0.20	0.008
P	0.50	0.020
P1	1.00	0.039
X	0.20	0.008
X1	0.40	0.016
Y	0.68	0.027
Y1	1.55	0.061
Z	1.55	0.061

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
0524P	DFN2510-10L	3000PCS	7"

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